- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

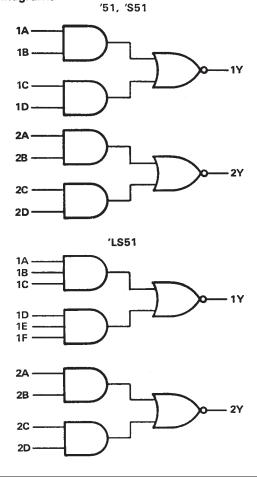
description

The '51 and 'S51 contain two independent 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{AB + CD}$.

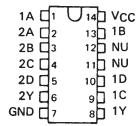
The 'LS51 contains one 2-wide 3-input and one 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean functions $1Y = \overline{(1A \cdot 1B \cdot 1C) + (1D \cdot 1E \cdot 1F)}$ and $2Y = \overline{(2A \cdot 2B) + (2C \cdot 2D)}$.

The SN5451, SN54LS51, and SN54S51 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN7451, SN74LS51 and SN74S51 are characterized for operation from 0°C to 70°C.

logic diagrams



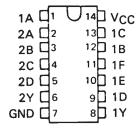
SN5451 . . . J PACKAGE SN54S51 . . . J OR W PACKAGE SN7451 . . . N PACKAGE SN74S51 . . . D OR N PACKAGE (TOP VIEW)



SN5451 . . . W PACKAGE (TOP VIEW)

ī	U 14] 1D
2	13] 1C
3	12	D 1Y
4	11	☐ GND
5	10] 2Y
6	9	2D
7	8] 2C
	3 4 5	3 12 4 11 5 10 6 9

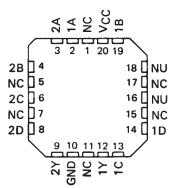
SN54LS51 . . . J OR W PACKAGE SN74LS51 . . . D OR N PACKAGE (TOP VIEW)



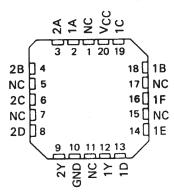
NC- No internal connection
NU - Make no external connection



SN54S51 . . . FK PACKAGE (TOP VIEW)

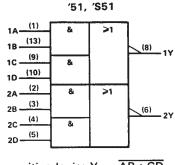


SN54LS51 . . . FK PACKAGE (TOP VIEW)

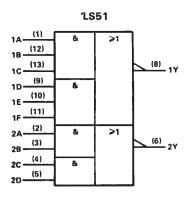


NC - No internal connection
NU - Make no external connection

logic symbols†



positive logic: $Y = \overline{AB + CD}$



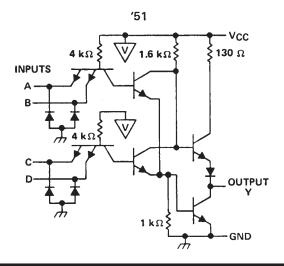
positive logic:

$$1Y = \overline{(1A \cdot 1B \cdot 1C) + (1D \cdot 1E \cdot 1F)}$$

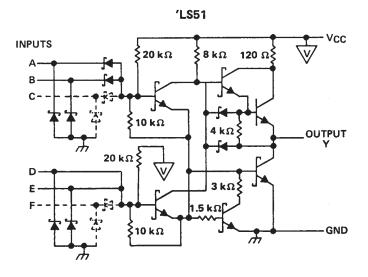
$$2Y = \overline{(2A \cdot 2B) + (2C \cdot 2D)}$$

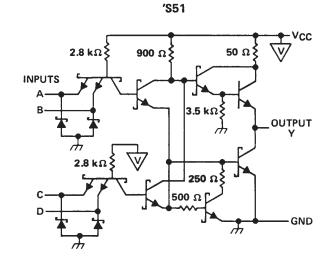
[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

schematics









absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1): '	51, 'LS51, 'S51	7 V
Input voltage: '51, 'S51		5.5 V
′LS51		7 V
Operating free-air temperature range:	SN54'	-55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5451			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.8			0.8	V
Іон	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			16			16	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T. 0.10 .		SN5451			SN7451	-	UNIT
PARAMETER	т	EST CONDI	TIONS †	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	UNII
VIK	V _{CC} = MIN, I ₁ =	- 12 mA				– 1.5			1.5	٧
Voн		= 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		>
VOL	V _{CC} = MIN, V _{II}	₁ = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	>
l _l	V _{CC} = MAX, V _I	= 5.5 V				1			1	mA
ЧН	V _{CC} = MAX, V ₁	= 2.4 V				40			40	μΑ
I _I L	V _{CC} = MAX, V _I	= 0.4 V				– 1.6			– 1.6	mA
1088	V _{CC} = MAX	<u> </u>		- 20		- 55	- 18		- 55	mA
¹ ССН	V _{CC} = MAX, V _I	= 0 V			4	8		4	8	mA
ICCL	V _{CC} = MAX, See	Note 2			7.4	14		7.4	14	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
^t PLH	A	~	B. = 400 O	C ₁ = 15 pF		13	22	ns
tPHL	Any	1	R _L = 400 Ω,	C[- 15 pr		8	15	115

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25 $^{\circ}$ C. § Not more than one output should be shorted at a time.

recommended operating conditions

			N54LS	51		SN74LS	51	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.7			8.0	V
10Н	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEOT 00415	UZIONO A	S	N54LS5	51	S	N74LS	51	UNIT
PARAMETER		TEST COND	II I I ONS T	MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				– 1. 5			– 1.5	· V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		>
V	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 8 mA					0.35	0.5	· ·
lj	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
IН	V _{CC} = MAX,	V _I = 2.7 V				20			20	μΑ
lı.	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA
IOS§	V _{CC} = MAX			- 20		100	- 20		100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			8.0	1.6		8.0	1.6	mA
ICCL	V _{CC} = MAX,	See Note 2			1,4	2.8		1.4	2.8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN TYP	MAX	UNIT
tPLH		V	D210	C15 pc	12	20	ns
tPHL	Any	Y	$R_L = 2 k\Omega$,	C _L = 15 pF	12.5	20	กร

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

			SN54S5	1		SN74S5	1	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
Іон	High-level output current			-1			- 1	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS †				1		UNIT		
PARAMETER		TEST COND	ITIONS †	MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				1.2			1.2	V
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 20 mA			0.5			0.5	V
Ц	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V _I = 2.7 V				50			50	μΑ
I _Ι Ε	V _{CC} = MAX,	V ₁ = 0.5 V				-2			-2	mA
loss	V _{CC} = MAX			- 40		- 100	40		100	mA
¹ ссн	V _{CC} = MAX,	V _I = 0 V			8.2	17.8		8.2	17.8	mA
ICCL	V _{CC} = MAX,	See Note 2			13.6	22		13.6	22	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
tPLH			D - 200 C	C = 15 oF	3.5	5.5	ns
tPHL	_		R _L = 280 Ω,	C _L = 15 pF	3.5	5.5	ns
^t PLH	Any	Y	R _L = 280 Ω,	C ₁ = 50 pF	5		ns
t _{PHL}			L 200 ts,	o <u>r</u> 00 h.	5.5		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00502BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
JM38510/07401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
JM38510/07401BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
JM38510/30401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
JM38510/30401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
M38510/00502BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
M38510/00502BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
M38510/07401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
M38510/07401BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
M38510/30401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
M38510/30401BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
SN5451J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5451J	Samples
SN5451J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5451J	Samples
SN54LS51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS51J	Samples
SN54LS51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS51J	Samples
SN54S51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S51J	Samples
SN74LS51D	OBSOLETI	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS51	





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS51D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS51	
SN74LS51DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS51N	Samples
SN74LS51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS51N	Samples
SN74LS51NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS51	Samples
SN74LS51NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS51	Samples
SN74S51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S51	Samples
SN74S51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S51	Samples
SN74S51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S51N	Samples
SN74S51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S51N	Samples
SNJ5451J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451J	Samples
SNJ5451J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451J	Samples
SNJ5451W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451W	Samples
SNJ5451W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451W	Samples
SNJ54LS51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51J	Samples
SNJ54LS51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51J	Samples
SNJ54LS51W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51W	Samples
SNJ54LS51W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51W	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54S51FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 51FK	Samples
SNJ54S51J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S51J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54LS51, SN54S51, SN74LS51, SN74S51:

● Catalog : SN74LS51, SN74S51

Military: SN54LS51, SN54S51

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS51DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS51NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS51DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS51NSR	SOP	NS	14	2000	356.0	356.0	35.0



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PACKAGE MATERIALS INFORMATION

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07401BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/07401BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ5451W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS51W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54S51FK	FK	LCCC	20	55	506.98	12.06	2030	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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